seeed studio

reComputer Jetson-10-1-H0

Introduction

reComputer Jetson-10-1 series are compact edge computers built with NVIDIA advanced AI embedded system Jetson Nano and Seeed reference carrier board v1.

With rich extension modules, industrial peripherals, thermal management combined with decades of Seeed Studio hardware expertise, reComputer Jetson is ready to help you accelerate and scale the next-gen AI product emerging diverse AI scenarios.

reComputer Jetson is compatible with the entire NVIDIA Jetson software stack, cloud-native workflows, industry- leading AI frameworks, helping deliver seamless AI integration.

Part list

- Jetson Nano x1
- Seeed reference carrier board x1
- Passive aluminum heatsink x1
- Aluminum case (black) x1
- 12V/2A power adapter (with 5 interchangeable adapter plugs) x1

Category

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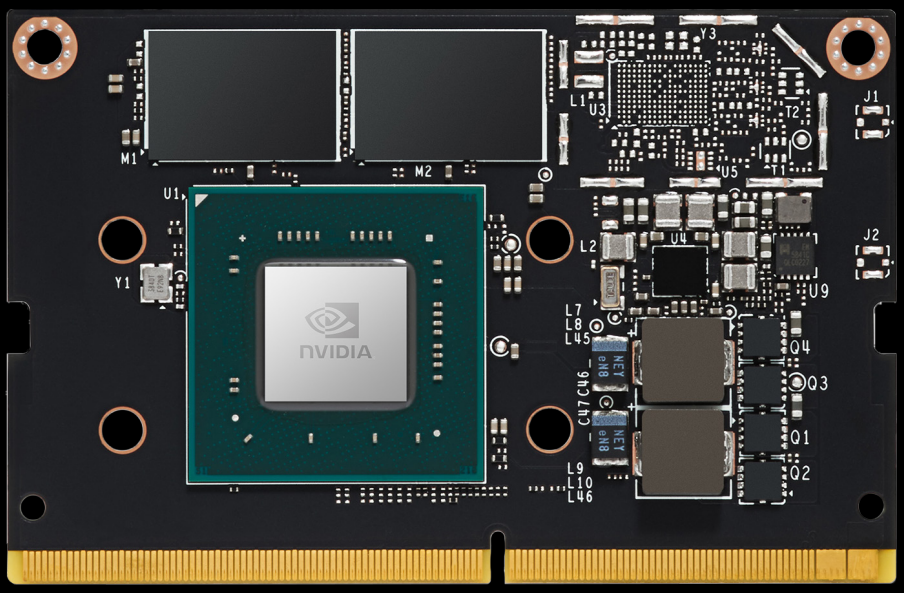
Module - Jetson Nano (production version)



A new dimension in AI

At just 70 x 45 mm, the Jetson Nano module is smaller than a credit card. But this production-ready System on Module (SOM) delivers big when it comes to deploying AI to devices at the edge across multiple industries—from smart cities and factories to agriculture and robotics.

Big compute perormance

Jetson Nano delivers 472 GFLOPs for taking on modern AI algorithms. It runs multiple neural networks in parallel and processes several high-resolution sensors simultaneously, making it ideal for applications ranging from NVRs to intelligent gateways.

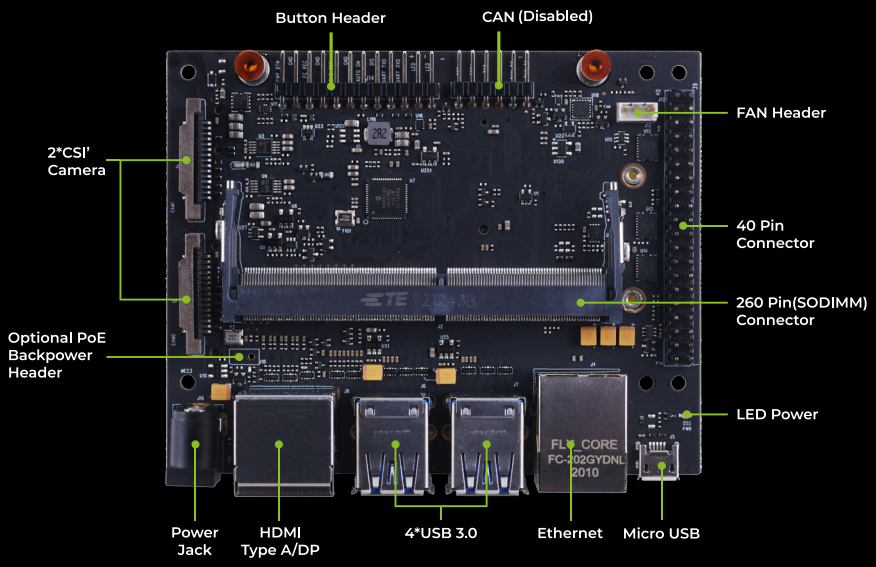
Low power demands

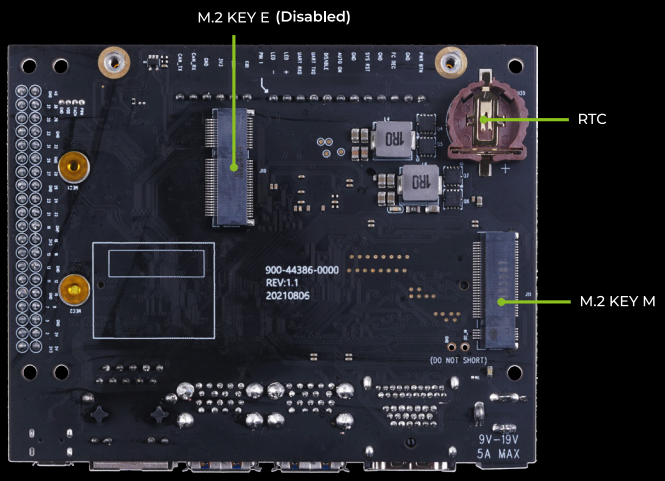
Now, you can innovate at the edge with powerful and efficient AI, computer vision, and high-performance computing at just 5 to 10 watts.

Module Technical Specifications

GPU	NVIDIA Maxwell architecture with 128 NVIDIA CUDA® cores
CPU	Quad-core ARM Cortex-A57 MPCore processor
Memory	4 GB 64-bit LPDDR4, 1600MHz 25.6 GB/s
Storage	16 GB eMMC 5.1
Video Encode	250MP/sec; 1x 4K @ 30 (HEVC); 2x 1080p @ 60 (HEVC) 4x 1080p @ 30 (HEVC); 4x 720p @ 60 (HEVC); 9x 720p @ 30 (HEVC)
Video Decode	500MP/sec; 1x 4K @ 60 (HEVC); 2x 4K @ 30 (HEVC) 4x 1080p @ 60 (HEVC); 8x 1080p @ 30 (HEVC); 9x 720p @ 60 (HEVC)
Camera	12 lanes (3x4 or 4x2) MIPI CSI-2 D-PHY 1.1 (1.5 Gb/s per pair)
Connectivity	M.2 Key M
	10/100/1000 BASE-T Ethernet
Display	HDMI 2.0 and eDP 1.4
I/O	1x SDIO / 2x SPI / 4x I2C / 2x I2S / GPIOs -> I2C, I2S
UPHY	1 x1/2/4 PCIE, 1x USB 3.0, 3x USB 2.0
Size	69.6 mm x 45 mm
Mechanical	260-pin edge connector

Seeed reference Carrier Board v1





Note: When Jetson Nano is used, the M.2 E KEY and CAN cannot work

The Seeed reference carrier board provides several connectors with industry standard pin outs to support additional functionality beyond what is integrated on the main platform board. These connectors are:

- USB 2.0: Micro B Connector
- USB 3.0: 4 x Type A Connectors
- Gigabit Ethernet: RJ45 Connector
- HDMI / DP: HDMI Type A and DisplayPort Stacked Connector
- M.2 Key M Socket

USB Port

The carrier board supports two USB Connectors. One is a USB 2.0 Micro B connector supporting Device mode only (including USB Recovery). There are two, dual stacked USB 3.0 Type A connectors. Each connector supports Host mode only. A single load switch supplies VBUS to all four USB 3.0 ports and is limited to 2A of output current.

USB 2.0 Micro B Connector Pin Description:

Pin #	Module Pin Name	Usage and Description	Type/Dir
1	–	VBUS Supply	Power
2	USB0_D_N	USB 2.0 #0 Data	Bidir
3	USB0_D_P		
4	–	Unused	Unused
5	–	Ground	Ground

Note:
In the Type/Dir column, Output is to USB connector. Input is form USB connector. Bidir is for bidirectional signals.

USB 3.0 Type A Connector Pin Descriptions:

Pin #	Module Pin Name[1]	Usage/Description	Type/Dir[2]
USB 3.0 Type A (2)			
1	–	VBUS Supply	Power
2	USB1_D_N	USB 2.0 #2 Data from hub	Bidir
3	USB1_D_P		
4	–	Ground	Ground
5	USBSS_RX_N	USB 3.0 Receive #2 Data from hub	Input
6	USBSS_RX_P		
7	–	Ground	Ground
8	USBSS_TX_N	USB 3.0 Transmit #2 Data from hub	Output
9	USBSS_TX_P		
USB 3.0 Type A (1)			
10	–	VBUS Supply	Power
11	USB1_D_N	USB 2.0 Data #1 Data from hub	Bidir
12	USB1_D_P		
13	–	Ground	Ground
14	USBSS_RX_N	USB 3.0 Receive #1 Data from hub	Input
15	USBSS_RX_P		
16	–	Ground	Ground
17	USBSS_TX_N	USB 3.0 Transmit #1 Data from hub	Output
18	USBSS_TX_P		

Note:
1. The module pin names not directly connected to the USB connector pins but are routed to the input of the USB hub.
2. In the Type/Dir column, Output is to USB connectors. Input is from USB connectors. Bidir is for bidirectional signals.

USB 3.0 Type A Connector Pin Descriptions:

Pin #	Module Pin Name[1]	Usage/Description	Type/Dir[2]
USB 3.0 Type A (4)			
1	–	VBUS Supply	Power
2	USB1_D_N	USB 2.0 #4 Data from hub	Bidir
3	USB1_D_P		
4	–	Ground	Ground
5	USBSS_RX_N	USB 3.0 Receive #4 Data from hub	Input
6	USBSS_RX_P		
7	–	Ground	Ground
8	USBSS_TX_N	USB 3.0 Transmit #4 Data from hub	Output
9	USBSS_TX_P		
USB 3.0 Type A (3)			
10	–	VBUS Supply	Power
11	USB1_D_N	USB 2.0 Data #3 Data from hub	Bidir
12	USB1_D_P		
13	–	Ground	Ground
14	USBSS_RX_N	USB 3.0 Receive #3 Data from hub	Input
15	USBSS_RX_P		
16	–	Ground	Ground
17	USBSS_TX_N	USB 3.0 Transmit #3 Data from hub	Output
18	USBSS_TX_P		

Note:
1. The module pin names not directly connected to the USB connector pins but are routed to the input of the USB hub.
2. In the Type/Dir column, Output is to USB connectors. Input is from USB connectors. Bidir is for bidirectional signals.

Gigabit Ethernet

Ethernet RJ45 Connector Pin Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir
1	GPE_MDI0_P	Gigabit Ethernet MDI 0+	Bidir
2	GPE_MDI0_N	Gigabit Ethernet MDI 0–	Bidir
3	GPE_MDI1_P	Gigabit Ethernet MDI 1+	Bidir
4	–	MCT	–
5	–	MCT	–
6	GPE_MDI1_N	Gigabit Ethernet MDI 1–	Bidir
7	GPE_MDI2_P	Gigabit Ethernet MDI 2+	Bidir
8	GPE_MDI2_N	Gigabit Ethernet MDI 2–	Bidir
9	GPE_MDI3_P	Gigabit Ethernet MDI 3+	Bidir
10	GPE_MDI3_N	Gigabit Ethernet MDI 3–	Bidir
11	–	Power-Over-Ethernet	Power
12			
13			
14			
15	–	Green LED Anode	Input
16	GBE_LED_LINK	Green LED Cathode. On for 1000Mbps link. Off for 10/100Mbps.	Output
17	–	Yellow LED Anode	Input
18	GBE_LED_ACT	Yellow LED Cathode. On indicates activity.	Output
19	–	Shield Ground	Ground
20			

Note:
In the Type/Dir column, Output is to RJ45 connector. Input is from RJ45 connector.
Bidir is for bidirectional signals.

HDMI and DisplayPort

HDMI Connector Pin Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir
1	DP1_TXD0_P	HDMI Transmit Data 2+	Output
2	–	Ground	Ground
3	DP1_TXD0_N	HDMI Transmit Data 2–	Output
4	DP1_TXD1_P	HDMI Transmit Data 1+	Output
5	–	Ground	Ground
6	DP1_TXD1_N	HDMI Transmit Data 1–	Output
7	DP1_TXD2_P	HDMI Transmit Data 0+	Output
8	–	Ground	Ground
9	DP1_TXD2_N	HDMI Transmit Data 0–	Output
10	DP1_TXD3_P	HDMI Transmit Clock+	Output
11	–	Ground	Ground
12	DP1_TXD3_N	HDMI Transmit Clock–	Output
13	HDMI_CEC	HDMI CEC	Bidir
14	–	Unused	Unused
15	DP1_AUX_P	HDMI DDC Clock	Output /OD
16	DP1_AUX_N	HDMI DDC Data	Bidir/OD
17	–	Ground	Ground
18	–	HDMI 5V Power	Power
19	DP1_HPD	HDMI Hot Plug Detect	Input

Note:
In the Type/Dir column, Output is to HDMI connector. Input is from HDMI connector. Birdir is for bidirectional signals.

DP Connector Pin Description:

DP	Module Pin Name	Usage/Description	Type/Dir
1	DP0_TXD0_P	DP Lane 0+	Output
2	–	Ground	Ground
3	DP0_TXD0_N	DP Lane 0–	Output
4	DP0_TXD1_P	DP Lane 1+	Output
5	–	Ground	Ground
6	DP0_TXD1_N	DP Lane 1–	Output
7	DP0_TXD2_P	DP Lane 2+	Output
8	–	Ground	Ground
9	DP0_TXD2_N	DP Lane 2–	Output
10	DP0_TXD3_P	DP Lane 3+	Output
11	–	Ground	Ground
12	DP0_TXD3_N	DP Lane 3–	Output
13	–	MODE: Selects between DP and TMDS (DV	Unused
14	–	CEC_DP: Not used – pulled to GND throug	Unused
15	DP0_AUX_N	DisplayPort Auxiliary Channel 0-	Bidir
16	–	Ground	Ground
17	DP0_AUX_P	DisplayPort Auxiliary Channel 0+	Bidir
18	DP0_HPD	HDMI Hot Plug Detect	Input
19	–	Power Return (Ground)	Ground
20	–	+3.3V	Power

Note:
In the Type/Dir column, Output is to DP connector. Input is from DP connector. Bidir is for bidirectional signals.

M.2 Key E Expansion Slot

M.2 Key M Expansion Slot Pin Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir Default
1	–	Ground	Ground
3			
5	PCIE0_RX3_N	PCIe IF #0 Lane 3 Receive	Input
7	PCIE0_RX3_P		
9	–	Ground	Ground
11	PCIE0_TX3_N	PCIe IF #0 Lane 3 Transmit	Output
13	PCIE0_TX3_P		
15	–	Ground	Ground
17	PCIE0_RX2_N	PCIe IF #0 Lane 2 Receive	Input
19	PCIE0_RX2_P		
21	–	Ground	Ground
23	PCIE0_TX2_N	PCIe IF #0 Lane 2 Transmit	Output
25	PCIE0_TX2_P		
27	–	Ground	Ground
29	PCIE0_RX1_N	PCIe IF #0 Lane 1 Receive	Input
31	PCIE0_RX1_P		
33	–	Ground	Ground
35	PCIE0_TX1_N	PCIe IF #0 Lane 1 Transmit	Output
37	PCIE0_TX1_P		
39	–	Ground	Ground
41	PCIE0_RX0_N	PCIe IF #0 Lane 0 Receive	Input
43	PCIE0_RX0_P		
45	–	Ground	Ground
47	PCIE0_TX0_N	PCIe IF #0 Lane 0 Transmit	Output
49	PCIE0_TX0_P		
51	–	Ground	Ground
53	PCIE0_CLK_N	PCIe IF #0 Reference Clock	Output
55	PCIE0_CLK_P		
57	–	Ground	Ground
59	–	Unused (Key)	Unused
61			
63			
65			
67	–	Unused	Unused
69			
71	–	Ground	Ground
73			
75			

Pin #	Module Pin Name	Usage/Description	Type/Dir Default
2	–	Main 3.3V Supply	Power
4			
6	–	Unused	Unused
8			
10			
12	–	Main 3.3V Supply	Power
14			
16			
18			
20	–	Unused	Unused
22			
24			
26			
28			
30			
32			
34			
36			
38			
40	I2C2_SCL	General I2C #2 (optional)	Bidir/OD, 1.8V
42	I2C2_SDA		
44	SDMMC_DAT1	M.2 Key M Alert	Output, 1.8V
46	–	Unused	Unused
48			
50	PEX0_RST*	PCIe IF #0 Reset	Output, 3.3V
52	PEX0_ CLKREQ*	PCIe IF #0 Clock Request	Input, 3.3V
54	PEX_WAKE*	PCIe Wake (Level Shifted from 3.3V	Input, 3.3V
56	–	Unused	Unused
58			
60	–	Unused (Key)	Unused
62			
64			
66			
68	–	32KHz Suspend Clock	Output, 3.3V
70	–	Main 3.3V Supply	Power
72			
74			

Note:
In the Type/Dir column, Output is to M.2 module. Input is from M.2 Module. Bidir is for bidirectional signals.

Camera Connector

Camera 0 Connector Pin Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir
1	–	Ground	Ground
3	CSI0_D0_N	CSI 0 Data 0	Input
5	CSI0_D0_P		
7	–	Ground	Ground
9	CSI0_D1_N	CSI 0 Data 1	Input
11	CSI0_D1_P		
13	–	Ground	Ground
15	CSI0_CLK_N	CSI 0 Clock	Input
17	CSI0_CLK_P		
19	–	Ground	Ground
21	CAM0_PWDN	Camera #0 Power-down	Output, 1.8V
23	CAM0_MCLK	Camera #0 Master Clock	Output, 1.8V
25	CAM_I2C_SCL	Camera I2C. 2.2kΩ pull ups on module. 1.6kΩ pull-ups on the carrier board. The module CAM_I2C pins connect to an I2C mux. The camera connector #1 receives the I2C from the mux (1st output). The I2C signals on the camera side of the mux have 47kΩ pull-ups.	Output, 3.3V
27	CAM_I2C_SDA		Bidir, 3.3V
29	–	+3.3V	Power

Pin #	Module Pin Name	Usage/Description	Type/Dir
2	–	Not Used	–
4	–		
6	–		
8	–		
10	–		
12	–		
14	–		
16	–		
18	–		
20	–		
22	–		
24	–		
26	–		
28	–		
30	–		

Note:
In the Type/Dir column, Output is to camera module. Input is from camera module. Bidir is for bidirectional signals.

Camera 1 Connector Pin Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir
1	–	Ground	Ground
3	CSI2_D0_N	CSI 2 Data 0	Input
5	CSI2_D0_P		
7	–	Ground	Ground
9	CSI2_D1_N	CSI 2 Data 1	Input
11	CSI2_D1_P		
13	–	Ground	Ground
15	CSI2_CLK_N	CSI 2 Clock	Input
17	CSI2_CLK_P		
19	–	Ground	Ground
21	CAM1_PWDN	Camera #1 Power-down	Output, 1.8V
23	CAM1_MCLK	Camera #1 Master Clock	Output, 1.8V
25	CAM_I2C_SCL	Camera I2C. 2.2kΩ pull-ups on module. 1.6kΩ pull-ups on the carrier board. The module CAM_I2C pins connect to an I2C mux. The camera connector #2 receives the I2C from the mux (2nd output). The I2C signals on the camera side of the mux have 47kΩ pull-ups.	Output, 3.3V
27	CAM_I2C_SDA		Bidir, 3.3V
29	–	+3.3V	Power

Pin #	Module Pin Name	Usage/Description	Type/Dir
2	–	Not Used	–
4	–		
6	–		
8	–		
10	–		
12	–		
14	–		
16	–		
18	–		
20	–		
22	–		
24	–		
26	–		
28	–		
30	–		

Note:
In the Type/Dir column, Output is to camera module. Input is from camera module.
Bidir is for bidirectional signals.

40-Pin Expansion Header

40-pin : part 1

Header Pin #	Module Pin Name	SoC Pin name	Default Usage / Descripti	Alternate Functionality	Type/ Dir
1	–	–	Main 3.3V Supply	–	Power (input)
2	–	–	Main 5.0V Supply	–	Power (input/out
3	I2C1_SDA	DP_AUX_CH3_N	I2C #1 Data	–	Bidir OD
4	–	–	Main 5.0V Supply	–	Power
5	I2C1_SCL	DP_AUX_CH3_P	I2C #1 Clock	–	Bidir OD
6	–	–	Ground	–	Ground
7	GPIO09	AUD_MCLK	GPIO	Audio Master Clock	Bidir/Output
8	UART1_TXD	UART1_TX	UART #1 Transmit	GPIO	Output/Bidir
9	–	–	Ground	–	Ground
10	UART1_RXD	UART1_RX	UART #1 Receive	GPIO	Input/Bidir
11	UART1_RTS*	UART1_RTS	GPIO	UART #2 Request to Send	Bidir/Output
12	I2S0_SCLK	DAP5_SCLK	GPIO	Audio I2S #0 Clock	Bidir
13	SPI1_SCK	SPI3_SCK	GPIO	SPI #1 Shift Clock	Bidir/Output
14	–	–	Ground	–	Ground
15	GPIO12	TOUCH_CLK	GPIO	–	Bidir
16	SPI1_CS1I*	SPI3_CS1	GPIO	SPI #1 Chip Select #1	Bidir/Output
17	–	–	Main 3.3V Supply	–	Power
18	SPI1_CSI0*	SPI3_CS0	GPIO	SPI #0 Chip Select #0	Bidir/Output
19	SPI0_MOSI	SPI1_MOSI	GPIO	SPI #0 Master Out/Slave In	Bidir/Output
20	–	–	Ground	–	Ground
21	SPI0_MISO	SPI1_MISO	GPIO	SPI #0 Master In/Slave Out	Bidir/Input
22	SPI1_MISO	SPI3_MISO	GPIO	SPI #1 Master In/Slave Out	Bidir/Input
23	SPI0_SCK	SPI1_SCK	GPIO	SPI #0 Shift Clock	Bidir/Output
24	SPI0_CS0*	SPI1_CS0	GPIO	SPI #0 Chip Select #0	Bidir/Output
25	–	–	Ground	–	Ground
26	SPI0_CS1*	SPI1_CS1	GPIO	SPI #0 Chip Select #1	Bidir/Output
27	I2C0_SDA	GEN2_I2C_SDA	I2C #0 Data	GPIO	Bidir OD/Bidir
28	I2C0_SCL	GEN2_I2C_SCL	I2C #0 Clock	GPIO	Bidir OD/Bidir
29	GPIO01	SOC_GPIO41	GPIO	General Purpose Clock #0	Bidir/Output
30	–	–	Ground	–	Ground
31	GPIO11	SOC_GPIO42	GPIO	General Purpose Clock #1	Bidir/Output
32	GPIO07	SOC_GPIO44	GPIO	PWM	Bidir/Output
33	GPIO13	SOC_GPIO54	GPIO	PWM	Bidir/Output
34	–	–	Ground	–	Ground
35	I2S0_FS	DAP5_FS	GPIO	Audio I2S #0 Field Select	Bidir
36	UART1_CTS*	UART1_CTS	GPIO	UART #1 Clear to Send	Bidir/Input
37	SPI1_MOSI	SPI3_MOSI	GPIO	SPI #1 Master Out/Slave In	Bidir/Output
38	I2S0_DIN	DAP5_DIN	GPIO	Audio I2S #0 Data in	Bidir/Input
39	–	–	Ground	–	Ground
40	I2S0_DOUT	DAP5_DOUT	GPIO	Audio I2S #0 Data Out	Bidir/Output

40-pin : part 2

Header Pin #	Pin Drive	SoC GPIO Port #	Power- on Default	PU/PD on Module	Notes
1	1A	–	–	–	1
2	1A	–	–	–	1
3	±2mA	–	z	2.2KΩ PU	2
4	1A	–	–	–	–
5	±2mA	–	z	2.2KΩ PU	2
6	–	–	–	–	–
7	±20uA	PS.04	pd		3
8	±20uA	PR.02	pd		3
9	–	–	–	–	–
10	±20uA	PR.03	pu		3
11	±20uA	PR.04	pd		3
12	±20uA	PT.05	pd		3
13	±20uA	PY.00	pd		3
14	–	–	–	–	–
15	±20uA	PCC.04	pd		3
16	±20uA	PY.04	pu		3
17	1A	–	–	–	1
18	±20uA	PY.03	pu		3
19	±20uA	PZ.05	pd		3
20	–	–	–	–	–
21	±20uA	PZ.04	pd		3
22	±20uA	PY.01	pd		3
23	±20uA	PZ.03	pd		3
24	±20uA	PZ.06	pu		3
25	–	–	–	–	–
26	±20uA	PZ.07	pu		3
27	±2mA	PDD.00	z	2.2KΩ PU	2
28	±2mA	PCC.07	z	2.2KΩ PU	2
29	±20uA	PQ.05	pd		3
30	–	–	–	–	–
31	±20uA	PQ.06	pd		3
32	±20uA	PR.00	pd		3
33	±20uA	PN.01	pd		3
34	–	–	–	–	–
35	±20uA	PU.00	pd		3
36	±20uA	PR.05	pd		3
37	±20uA	PY.02	pd		3
38	±20uA	PT.07	pd		3
39	–	–	–	–	–
40	±20uA	PT.06	pd		3

Note:

1. This is current capability per power pin.

2. These pins are connected to the SoC directly. They are open-drain (either pulled up or driven low by the SoC when configured as outputs). The max drive that meets the data sheet VOL is ±2mA.

3. These pins connect to TI TXB0108 level translators. Due to the design of these devices, the output drivers are very weak, so they can be overdriven by another connected device output for bidirectional support.

4. In the Type/Dir column, output is to expansion header. Input is from expansion header. Bidir is for bidirectional signals. Where two directions are shown, the first is for the primary function (mostly GPIOs) and the second is for the alternate function.

5. Where the signal direction is input or output in this table (Table 3-3), this matches the typical special function usage (e.g. SPI, I2S, etc.). The direction is bidirectional if these are configured as GPIOs.

6. All signals on the 40-pin header are 3.3V levels.

Button Header

Button Header Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir Default
1	–	PC_LED- : Connects to LED Cathode to indicate System Sleep/Wake (Off when system in sleep mode)	Input, 5V
2	–	PC_LED+: Connects to LED Anode (see above)	Output
3	UART2_RXD (DEBUG)	UART #2 Receive	Input, 3.3V
4	UART2_TXD (DEBUG)	UART #2 Transmit	Output, 3.3V
5	–	AC OK: Connect pins 5 and 6 to disable Auto-Power-On and require power button press.	Input, 3.3V
6	–	Auto Power-on disable: Pulled to GND. See Pin 5.	na
7	–	Ground	Ground
8	SYS_RESET*	Temporarily connect pins 7 and 8 to reset system	Input, 1.8V
9	–	Ground	Ground
10	FORCE_RECOVERY*	Connect pins 9 and 10 during power-on to put system in USB Force Recovery mode.	Input, 1.8V
11	–	Ground	Ground
12	SLEEP/WAKE*	Connect pins 11 and 12 to initiate power-on if Auto-Power-	Input, 5V

Note:
In the Type/Dir column, Output is to button header. Input is from button header. Bidir is for bidirectional signals.

Fan Connector

Fan Connector Pin Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir Default
1	–	Ground	Ground
2	–	Main 5.0V Supply	Power
3	GPIO08	Fan Tachometer signal	Input, 5V
4	GPIO14	Fan Pulse Width Modulation signal	Output, 5V

Note:
In the Type/Dir column, Output is to fan connector. Input is from fan connector. Bidir is for bidirectional signals.

RTC-Coin Cell Batter Holder

Coin Cell Batter Holder Pin Description:

Pin #	Module Pin Name	Usage/Description	Type/Dir
1	PMIC_BBAT	Power Management IC (PMIC) real-time clock battery back-up. Optionally used to provide back-up power for the Real-Time-clock (RTC). Connects to coin cell (lithium or other). PMIC is supply when charging rechargeable cells. Coin cell is source when system is disconnected from power. Charging is enabled by default in soft-ware. If non-rechargeable battery is to be used, charging should be disabled.	Power (Bidir)
2	–	Ground	Ground
3	PMIC_BBAT	Same as pin #1	Power (Bidir)

DC Power Jack

Pin #	Module Pin Name	Usage/Description	Type/Dir Default
1	–	Main DC input supplying DC jack input (9-20V)	Power
2	–	Ground	Ground
3	–	Ground	Ground

Optional Power-Over Ethernet and Backpower Headers

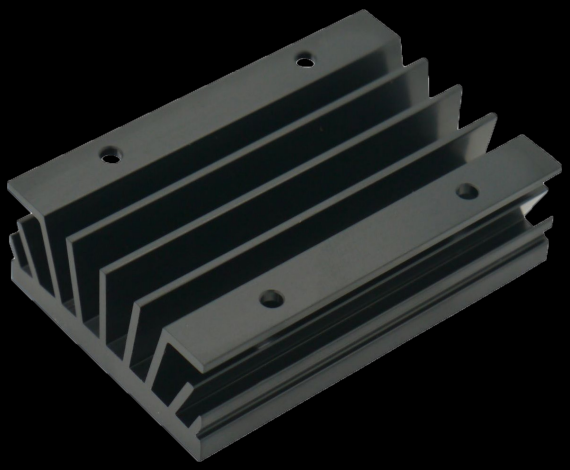
PoE Header:

Pin #	Module Pin Name	Usage/Description	Type/Dir Default
1	–	Ethernet RG45 connector PoE VC1 power	Power
2	–	Ethernet RG45 connector PoE VC2 power	Power
3	–	Ethernet RG45 connector PoE VC3 power	Power
4	–	Ethernet RG45 connector PoE VC4 power	Power

PoE Backpower Header:

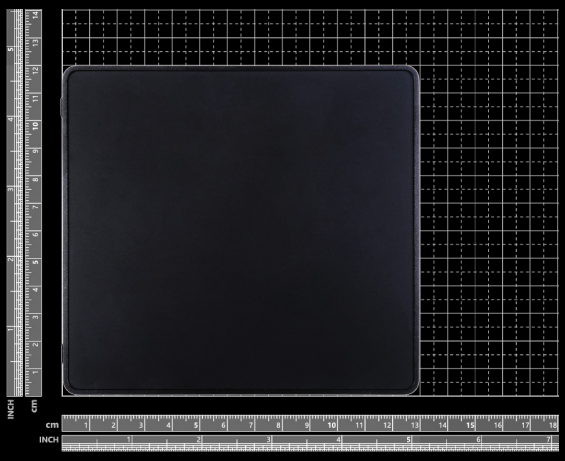
Pin #	Module Pin Name	Usage/Description	Type/Dir Default
1	–	Main DC input supplying DC jack input (9V-20V). 3A max.	Power
2	–	Ground	Ground

Passive aluminum heatsink



- Original NVIDIA Jetson Nano Passive Heat Sink
- Designed to fit the NVIDIA Jetson Nano modules
- Dimensions: 58.7 mm x 39.4mm x 17.3mm

Aluminium Heatsink



- Overall dimension: 130mm x120mm x 50mm

More information

Please check our Wiki and ask question at our Forum or Discord community.
For more information, you can also refer to NVIDIA official Jetson Download Center